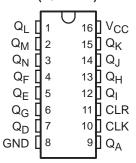
### SN54HC4020, SN74HC4020 14-BIT ASYNCHRONOUS BINARY COUNTERS

SCLS158E - DECEMBER 1982 - REVISED SEPTEMBER 2003

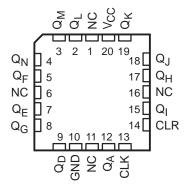
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I<sub>CC</sub>

SN54HC4020 . . . J OR W PACKAGE SN74HC4020 . . . D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



- Typical t<sub>pd</sub> = 12 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max

## SN54HC4020 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### description/ordering information

The 'HC4020 devices are 14-stage binary ripple-carry counters that advance on the negative-going edge of the clock pulse. The counters are reset to zero (all outputs low) independently of the clock (CLK) input when the clear (CLR) input goes high.

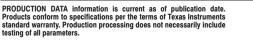
#### **ORDERING INFORMATION**

TA	PACKA	GE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC4020N	SN74HC4020N
		Tube of 40	SN74HC4020D	
	SOIC - D	Reel of 2500	SN74HC4020DR	HC4020
		Reel of 250	SN74HC4020DT	
-40°C to 85°C	SOP - NS	Reel of 2000	SN74HC4020NSR	HC4020
	SSOP - DB	Reel of 2000	SN74HC4020DBR	HC4020
		Tube of 90	SN74HC4020PW	
	TSSOP - PW	Reel of 2000	SN74HC4020PWR	HC4020
		Reel of 250	SN74HC4020PWT	
	CDIP – J	Tube of 25	SNJ54HC4020J	SNJ54HC4020J
−55°C to 125°C	CFP – W	Tube of 150	SNJ54HC4020W	SNJ54HC4020W
	LCCC – FK	Tube of 55	SNJ54HC4020FK	SNJ54HC4020FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



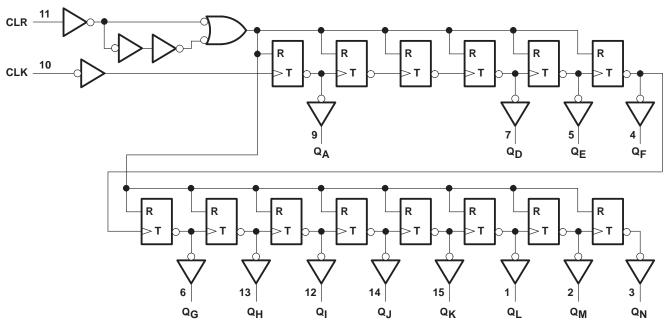
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# FUNCTION TABLE (each buffer)

INP	UTS	FUNCTION
CLK	CLR	FUNCTION
1	L	No change
$\downarrow$	L	Advance to next stage
Х	Н	All outputs L

#### logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see	e Note 1)	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	(see Note 1)	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$ .		±25 mA
Continuous current through V <sub>CC</sub> or GND		±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): I	D package	73°C/W
	DB package	82°C/W
	N package	67°C/W
	NS package	64°C/W
!	PW package	108°C/W
Storage temperature range, T <sub>sto</sub>		-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



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#### recommended operating conditions (see Note 3)

			SN	54HC40	20	SN	74HC40	20	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		V <sub>CC</sub> = 2 V	1.5			1.5			
VIH	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			3.15			V
		V <sub>CC</sub> = 6 V	4.2			4.2			
		V <sub>CC</sub> = 2 V			0.5			0.5	
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35			1.35	V
		VCC = 6 V			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		V <sub>CC</sub> = 2 V			1000			1000	
Δt/Δν	Input transition rise/fall time	V <sub>CC</sub> = 4.5 V			500			500	ns
		V <sub>C</sub> C = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			.,	Т	A = 25°C	;	SN54H	C4020	SN74H0	C4020	
PARAMETER	TEST CONDITIONS		VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20  \mu A$	4.5 V	4.4	4.499		4.4		4.4		
∨он	VOH VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I <sub>OL</sub> = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VOL	$V_I = V_{IH}$ or $V_{IL}$		6 V		0.001	0.1		0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_I = V_{CC}$ or 0,	I <sub>O</sub> = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

### SN54HC4020, SN74HC4020 14-BIT ASYNCHRONOUS BINARY COUNTERS

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# timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			\ ,_	T <sub>A</sub> = 1	25°C	SN54H	C4020	SN74H	C4020		
			VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V		5.5		3.7		4.3		
fclock	Clock frequency		4.5 V		28		19		22	MHz	
			6 V		33		22		25		
			2 V	90		135		115			
		CLK high or low	CLK high or low	4.5 V	18		27		23		
١.	Pode a demotion		6 V	15		23		20			
t <sub>W</sub>	Pulse duration		2 V	70		105		90		ns	
		CLR high	4.5 V	14		21		18			
			6 V	12		18		25			
			2 V	60		90		75			
t <sub>su</sub>	Setup time, CLR inactive before CLK $\downarrow$		4.5 V	12		18		15		ns	
			6 V	10		15		13			

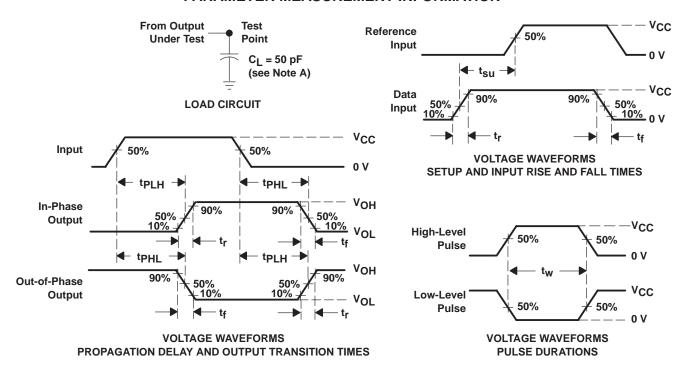
# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

545445755	FROM	то	,,	T	λ = 25°C	;	SN54H	C4020	SN74H	C4020	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	5.5	10		3.7		4.3		
f <sub>max</sub>			4.5 V	28	45		19		22		MHz
			6 V	33	53		22		25		
			2 V		62	150		225		190	
<sup>t</sup> pd	CLK	Q <sub>A</sub>	4.5 V		16	30		45		38	ns
·			6 V		12	26		38		32	
			2 V		63	140		210		175	
<sup>t</sup> PHL	CLR	Any	4.5 V		17	28		42		35	ns
			6 V		13	24		36		30	
			2 V		28	75		110		95	
t <sub>t</sub>		Any	4.5 V		8	15		22		19	ns
-			6 V		6	13		19		16	

### operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Ср	Power dissipation capacitance	No load	88	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_r = 6 \ ns$ ,  $t_f = 6 \ ns$ .
- C. For clock inputs, f<sub>max</sub> is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





16-Mar-2021

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
85003012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	85003012A SNJ54HC 4020FK	Samples
8500301EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8500301EA SNJ54HC4020J	Samples
8500301FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8500301FA SNJ54HC4020W	Samples
SN54HC4020J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC4020J	Samples
SN74HC4020D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4020	Samples
SN74HC4020DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4020	Samples
SN74HC4020N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC4020N	Samples
SN74HC4020NSR	ACTIVE	so	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4020	Samples
SN74HC4020PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4020	Samples
SN74HC4020PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4020	Samples
SN74HC4020PWT	ACTIVE	TSSOP	PW	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4020	Samples
SNJ54HC4020FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	85003012A SNJ54HC 4020FK	Samples
SNJ54HC4020J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8500301EA SNJ54HC4020J	Samples
SNJ54HC4020W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8500301FA SNJ54HC4020W	Samples

<sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

#### PACKAGE OPTION ADDENDUM



16-Mar-2021

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54HC4020, SN74HC4020:

Catalog: SN74HC4020

Military: SN54HC4020

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

### PACKAGE MATERIALS INFORMATION

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC4020DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC4020NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC4020PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC4020PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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\*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC4020DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC4020NSR	SO	NS	16	2000	853.0	449.0	35.0
SN74HC4020PWR	TSSOP	PW	16	2000	853.0	449.0	35.0
SN74HC4020PWT	TSSOP	PW	16	250	853.0	449.0	35.0

## W (R-GDFP-F16)

### CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

### N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



### FK (S-CQCC-N\*\*)

### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



### D (R-PDS0-G16)

#### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



# D (R-PDSO-G16)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



#### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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